1st generation

Between equipments (Inter-system EMC)





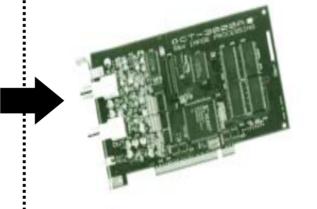


To meet regulations

Far field solution

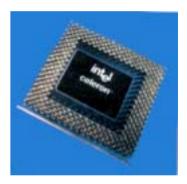
2nd generation

Inner the equipment (Intra-system EMC)



3rd generation

In the LSI (Micro-EMC)



To prevent the malfunction

Near field solution

To shape the waveform

High speed data transmission

Magnetic field solution